Title (en)

THERMAL INK JET PRINT HEAD ASSEMBLY

Publication

EP 0224937 A3 19881117 (EN)

Application

EP 86116956 A 19861205

Priority

US 80629485 A 19851206

Abstract (en)

[origin: EP0224937A2] In a thin film resistor substrate (32) for a thermal ink jet printhead, there is provided an elongated ink feed slot (16) for supplying ink to a plurality of heater resistors (36,38) on the substrate. Ink flows from this slot (16) vertically through the substrate (32) and then laterally along predetermined ink flow paths in an orifice plate (44) and barrier layer members to ink reservoirs (46,48) above the heater resistors (36,38). In this manner ink flow pressure drops to all of the reservoirs (46, 48) are equal and thereby enhance ink pressure control for all of the reservoirs (46, 48).

IPC 1-7

B41J 3/04

IPC 8 full level

B41J 2/05 (2006.01); **B41J 2/015** (2006.01); **B41J 2/14** (2006.01); **B41J 2/16** (2006.01); **B41J 2/175** (2006.01)

CPC (source: EP)

B41J 2/14024 (2013.01); **B41J 2/14145** (2013.01); **B41J 2/17513** (2013.01); B41J 2002/14387 (2013.01)

Citation (search report)

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